ECOREL™ EASY 802S-803S

INVENTEC PERFORMANCE CHEMICALS

Low residue no-clean solder pastes

FEATURES

ECOREL™ EASY 802 S / 803 S no-clean solder pastes have been developed for fine pitch printing. Applied by squeegees or closed head, the deposit has a very sharp definition even after several hours abandon time on stencil. Their rheological properties are suitable for “pin in paste” process.

SPECIFICATIONS

ECOREL™ EASY	802S	803S
Alloy	Sn62 Pb Ag2	Sn63 Pb
Melting point °C	178	183
Powder size distribution	25 - 45 microns	25 - 45 microns
Metal content (%)	89,5 ± 0.5	89,5 ± 0.5
Residue after reflow soldering (%)	57 – 64	57 – 64
Halogen content	no halogen	no halogen
Viscosity* (Pa.s at 20°C) ** Brookfield RVT, TF at 5 RPM*	650 – 850	650 – 850

CHARACTERISTICS

Long stencil life : more than 8 hrs.

Abandon time on the stencil more than 6 hrs with excellent print restart.

Printing speed : 60-150 mm/sec.

Solderballing resistance at high % RH.

Good wettability on all finishes.

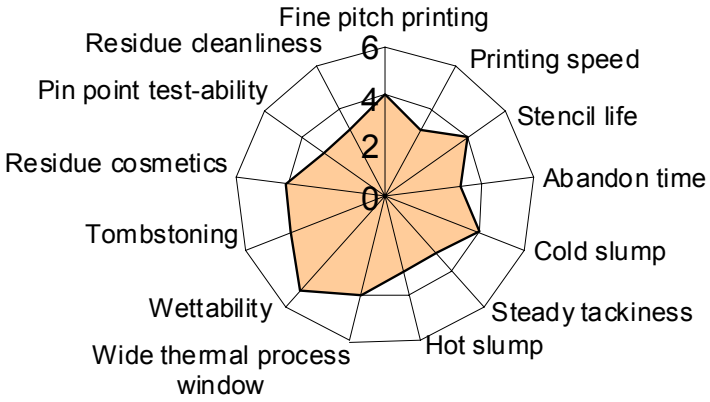
Stable tack : more than 16 hrs at 22°C between printing and component placement.

No slump out by preheat.

Slight yellow residue after reflow, pin point test probe compatible.

No halogen.

High SIR – No residue deterioration during accelerated ageing.



FUNCTI0NAL TESTS	Results	Procedures
Flux classification	RE L0	ANSI/J-STD-004
	F-SW 33	DIN 8511
	123	ISO 9454
Solderballing test	class 1	C 90550
Copper mirror	pass	ANSI/J-STD-004
Chromate paper	pass	ANSI/J-STD-004
Copper corrosion	pass	ANSI/J-STD-004
S.I.R. OHMS	pass	ANSI/J-STD-004
after 21 days		
85°C - 85 % RH - 50 Volts	> 10^9	
end of cycle		
20°C – 65 % RH	> 10^{10}	

PACKAGING

Jar	250 g or 500 g
Cartridge	700 g or 1400 g
PROFLOW cassette	800 g

STORAGE & SHELF LIFE

To ensure the best product performance, the recommended storage temperature range is 5°C to 10°C. For an optimal preservation, store cartridges in vertical position , tip downwards.

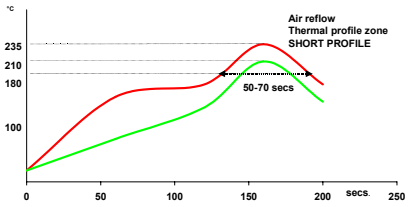
PROCESS PARAMETERS

Solder paste preparation

Before printing, it is essential to properly mix the solder paste, either manually with a spatula, or by doing several preliminary prints on the stencil.

Printing

ECOREL™ EASY 802 S and **ECOREL™ EASY 803 S** solder pastes are particularly easy to stencil print down to 0.3 mm pitch and up to 150 mm/sec. squeegee speed.

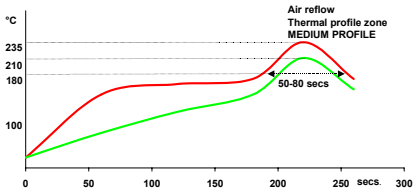


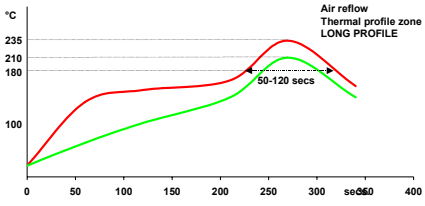
Reflow thermal profile

Graphs beside indicate, the optimal thermal profile zone according to PCB and component thermal mass.

A regular preheat temperature rise is preferable to a too long plateau, in order to avoid solder beading to get a shining joint and a uniform residue distribution.

Nitrogen atmosphere permits good coalescence and excellent wet ability inside a large reflow process window.





HSE

Contains lead. Do not handle without gloves. Read MSDS before use.

No issues when used as recommended.

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